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SEMICONDUCTOR DEVICE MANUFACTURING METHOD

ABSTRACT

[Problem] To provide a semiconductor device manufacturing method and a semiconductor device inspection method both of which are capable of efficiently inspecting individual LSI chips separated by cutting, as well as a jig for use in such methods.

[Means for Resolution] After a multiplicity of LSI chips are cut and separated from one semiconductor wafer, in the step of inspecting LSI chips, a predetermined number N of chips are rearranged and integrated by using a jig for integration which is formed of a material whose coefficient of thermal expansion approximates that of the chips and in which is formed an accommodating portion for rearranging the predetermined number N of chips, and the integrated predetermined number N of chips are subjected to a predetermined inspection process in a subsequent inspection step, whereby inspection efficiency is improved and inspection costs are reduced.

Figure 3

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